

### **STATUS OF THE CLAIMS**

The status of the claims of the present application stands as follows:

1. **(Canceled)**
2. **(Previously Presented)** An apparatus according to claim 21, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.
3. **(Previously Presented)** An apparatus according to claim 2, wherein said brush roller comprises an electrically conductive material.
4. **(Previously Presented)** An apparatus according to claim 3, wherein said brush roller comprises a polymer filled with an electrically-conductive material.
5. **(Previously Presented)** An apparatus according to claim 4, wherein said brush roller comprises a carbon-filled perfluoroalkoxyalkane.
6. **(Canceled)**
7. **(Previously Presented)** An apparatus according to claim 3, wherein said brush roller comprises a foam rubber cleaning portion.
8. **(Canceled)**
9. **(Canceled)**
10. **(Previously Presented)** A method of removing surface contaminants from a surface of a microelectronics wafer that may have a static electrical charge thereon, comprising the steps of:
  - (a) providing a microelectronics wafer having a surface; and
  - (b) cleaning said surface of said microelectronics wafer with a conductive rotating wafer-cleaning member so as to remove at least some of the surface contaminants, and so as to simultaneously create an electrical ground path between said surface and an electrical ground through said conductive rotating wafer-cleaning member.
11. **(Canceled)**

12. **(Canceled)**

13. **(Canceled)**

14. **(Currently Amended)** A method according to claim ~~13~~10, wherein step (b) includes contacting said surface with an electrically conductive wafer-cleaning brush roller having a non-filamentous cleaning surface.

15. **(Canceled)**

16. **(Canceled)**

17. **(Previously Presented)** A system for removing surface contaminants from a surface, comprising:

- (a) a microelectronics wafer having a surface;
- (b) an electrical ground;
- (c) a wafer-cleaning region receiving said microelectronics wafer; and
- (d) a conductive rotating wafer-cleaning member operatively configured to engage said surface of microelectronics wafer in said wafer cleaning region so as to remove contaminants from said surface and provide part of a grounding path between said microelectronics wafer and said electrical ground for removing electrical charge from said microelectronics wafer.

18. **(Previously Presented)** A system according to claim 17, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.

19. **(Canceled)**

20. **(Canceled)**

21. **(Previously Presented)** An apparatus for cleaning surface contaminants from a microelectronics wafer, comprising:

- (a) a wafer cleaning region configured to receive a microelectronics wafer during cleaning;
- (b) a conductive rotating wafer-cleaning member designed to contact the microelectronics wafer during cleaning so as to remove surface contaminants from the microelectronics wafer during cleaning; and

- (c) an electrical grounding path extending from the microelectronic wafer through said conductive rotating wafer-cleaning member to an electrical ground when the apparatus is connected to the electrical ground.